





AUTOMOTIVE ▲ Si MOSFET RELAY





SILICON Si MOSFET RELAY ▲ SMD type Switches AC or DC load AEC-Q101 qualified Input TTL / CMOS compatible Moisture Sensitivity Level ▲ MSL 3 UL 1577 approved ▲ File no E344988







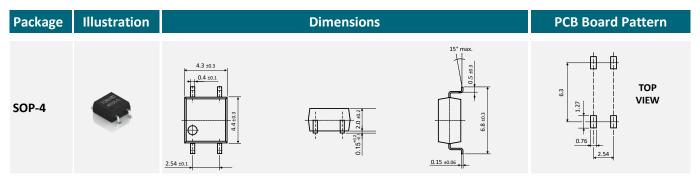
SPECIFICATION

Item		Characteristics		
Contact Form		1 Form A ▲ Normally open switch		
Load Voltage V _L		400V		
Operation LED Current IFON		3mA		
Load Current	I _L	100mA		
On-Resistance	Ron	20Ω		
Output Capacitance	C _{OUT}	52pF		
Low Off-State Leakage Current	I _{LEAK}	1μA at 400V _{DC}		

APPLICATIONS

Automatic Test	Electric	I/O	Industrial	Measurement	Security	Sensing
Equipment	Mobility	Modules	Automation	Equipment	Equipment	Equipment
	عال⊄		0	0		

DIMENSIONS, PIN DESCRIPTION AND PART NUMBER



Circuit Diagram	Pin Description	Part No.	Package	Packing
4 3	1 Anode (+) • LED 2 Cathode (-) • LED 3,4 Drain • MOSFET	AB30S-Q AB30S-Q-R1	SOP-4 SOP-4	Tube (100pcs) Reel (1000pcs)

MGT ▲ Manufacturer Group of Technology



ABSOLUTE MAXIMUM RATINGS ▲ AMBIENT TEMPERATURE T_A = 25°C

	ltem	Condition	Symbol	Value	Unit
	Outline package			SOP-4	
Туре	Part number			AB30S-Q	
	Output channels			1	Channel
	Continuous LED Current		IF	50	mA
Immud	Peak LED Current	100 Hz, Duty 1%	I _{FP}	500	mA
Input	LED Reverse Voltage		V_{R}	5	V
	Input Power Dissipation		P _{IN}	75	mV
	Load Voltage		V_L	400 (AC peak or DC)	V
Output	Load Current		I _L	100	mA
Output	Peak Load Current	1 ms, 1 shot	I _{PEAK}	600	mA
	Output Power Dissipation		Pout	300	mW
	Total Power Dissipation		P_{T}	350	mW
Polov	I/O Breakdown Voltage		V _{I/O}	1500	V _{RMS}
Relay	Operating Temperature Range		T_OPR	-40 to +105	°C
	Storage Temperature Range		T _{STG}	-40 to +125	°C

ELECTRICAL CHARACTERISTICS ▲ **AMBIENT TEMPERATURE** T_A = 25°C

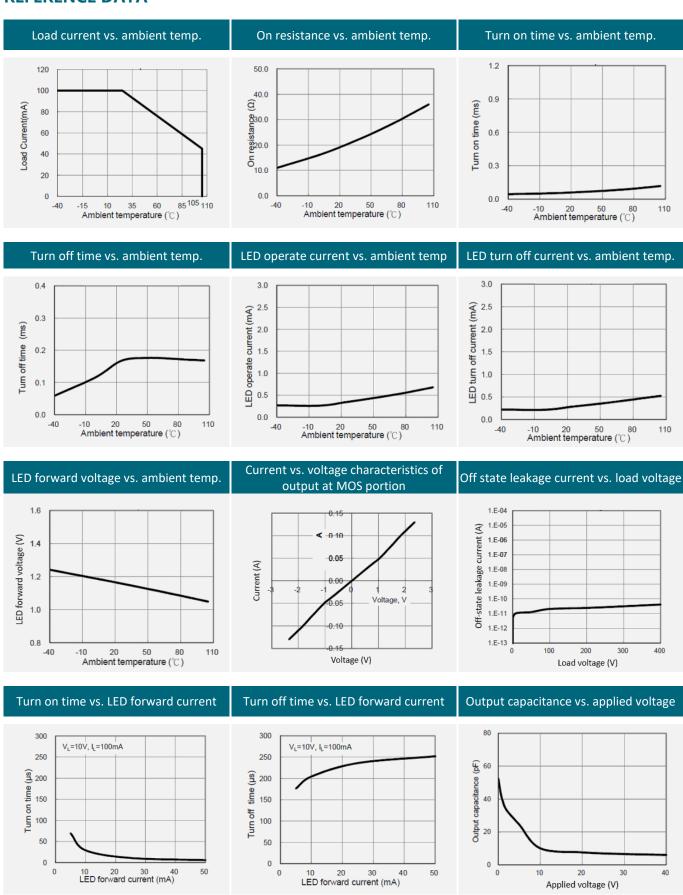
	Item	Condition	Symbol	Min.	Тур.	Max.	Unit
	LED Forward Voltage	I _F = 10mA	VF	0.9	1.17	1.5	V
Input	Operation LED Current		I _F ON		0.4	3	mA
	Recovery LED Voltage		V _F OFF	0.5	1		V
Outout	On-Resistance Drain to Drain (tested within 1 sec.)	I _F =5mA, I _L =Rating	Ron		20	24	Ω
Output	Off-State Leakage Current	V _L = 400V	I _{LEAK}			1	μΑ
	Output Capacitance	V _L =0V, f=1MHz	C _{OUT}		52		pF
Trans-	Turn-On Time	I _F =5mA, I _L =Rating	ton		0.1	0.5	ms
mission	Turn-Off Time	I _F =5mA, I _L =Rating	toff		0.2	0.5	ms
Carrelad	I/O Insulation Resistance		R _{I/O}	10 ⁹			Ω
Coupled	I/O Capacitance	f=1MHz	C _{I/O}		1.3		pF

RECOMMENDED OPERATING CONDITION ▲ AMBIENT TEMPERATURE T_A = 25°C

	Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Input	Continuous LED Current		l _F	5	10	15	mA
Output	Load Voltage		V_L			200	V
	Load Current		IL			50	mA



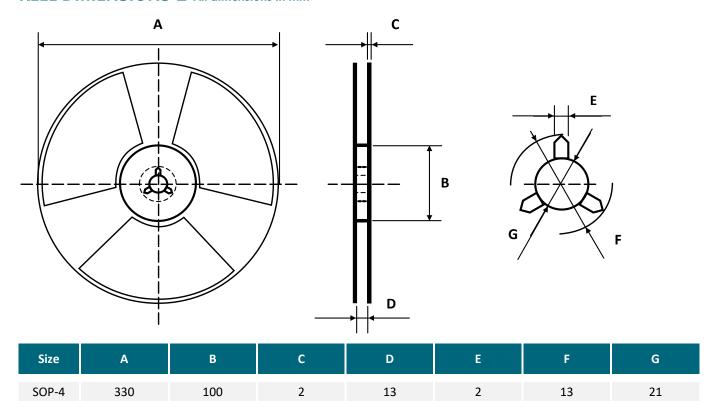
REFERENCE DATA



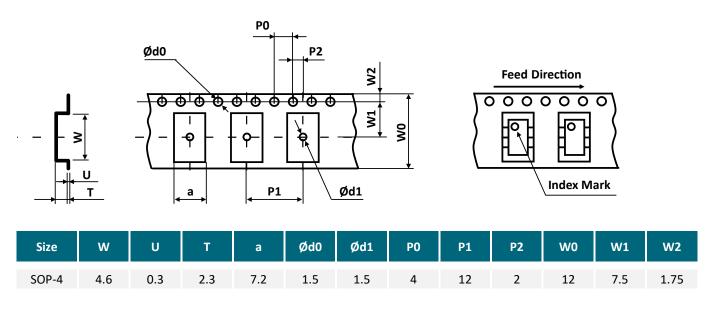
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REEL DIMENSIONS ▲ All dimensions in mm



TAPE DIMENSIONS ▲ All dimensions in mm





PACKING QUANTITIES

Tape and Reel Packing	PCS/Reel
SOP-4	1000

Tube Packing	PCS/Tube	Tubes/Box	Units/Box
SOP-4	100	30	3000

STORAGE AND HANDLING CONDITIONS

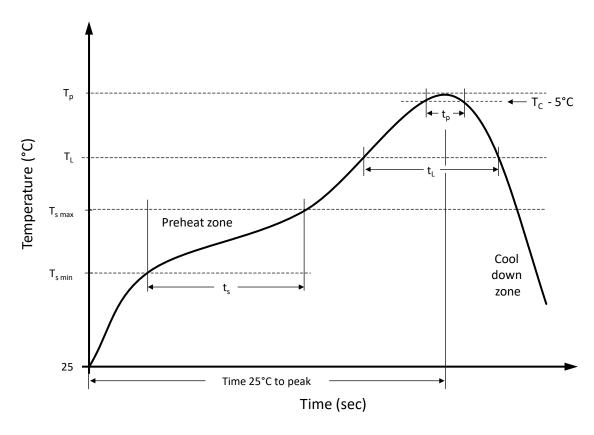
ESD level	Floor life	Conditions	MSL
HBM class 2	Unlimited	T _A < 30°C, RH < 85%	1

LOAD CONNECTING METHOD

Туре	Load	Connection	Feature
4 pins	AC or DC	V _L (AC or DC)	Control bi-directional signal



RECOMMENDED REFLOW SOLDERING PROFILE A SMD PACKAGE



Recommended reflow soldering conditions ▲ Refer to JEDEC J-STD-020E

Profile Features		Sn-Pb Eutetic Assembly	Pb-Free Assembly
Preheat temperature min.	T _{s min}	100 °C	150 °C
Preheat temperature max.	T _{s max}	150 °C	200 °C
Preheat time ts from Ts min to Ts max	ts	120 seconds	120 seconds
Ramp-up rate (Tւ to T♭)		max. 3 °C/second	max. 3 °C/second
Liquidous temperature	T_L	183 °C	217 °C
Time t _L maintained above T _L	t_{\scriptscriptstyleL}	150 seconds max.	60 seconds max.
Peak package body temperature	Tp	235°C	260°C
Timeframe of within 5°C below and up to max actual peak body temperature	tp	20 seconds max.	30 seconds max.
Ramp-down rate (T∟ to Tp)		max. 6 °C/second	max. 6 °C/second
Time 25°C to peak temperature		max. 6 minutes	max. 8 minutes



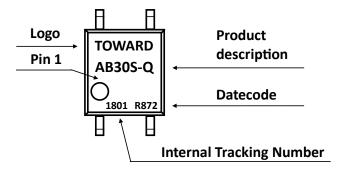
PRODUCT CODE

Example: AB30S-Q series ▲ 1 Form A ▲ AEC-Q101 ▲ 400V ▲ SOP-4 ▲ Tape & Reel

	AB	3	0		S	(Q	R	1
	Package	Sei	ries	Ту	pe	Specia	l Suffix	Pac	king
АВ	4 Pin ▲ 1 Form A	30	400V	S	SOP	Q	AEC-Q101	Blank R1	Tube Reel

PRODUCT MARKING

Example: AB30S-Q series ▲ 1 Form A ▲ AEC-Q101 ▲ 400V ▲ SOP-4 ▲ Tape & Reel



DATE CODE

Example: R872

R		8		7		2	
Material Characteristics		Year		Month		Week of the Month	
R H	RoHS compliant Halogen free	8 9 A B C G	2018 2019 2020 2021 2022 2026	1 2 3 4 5 	Jan Feb Mar Apr May Dec	1 2 3 4	1 st 2 nd 3 rd 4 th



RELIABILITY TESTS **A STANDARD**

Standard: AEC-Q101, JESD22-A, J-STD-002

No.	Test	Test	Test	Test
-1101	1230	Specification	Standard	Result
1	Precondition	Temperature: 25°C ± 5°C; Humidity: 55% RH ± 10% Bake condition: Temperature: 125°C; Duration 24 hours Soak condition: Temperature: 60°C; Humidity: 60% RH	JESD22-A113	No abnormal phenomenon was found. Functional test passed.
2	Temperature Cycling Test	Temperature: 25°C ± 5°C; Humidity: 55% RH ± 15% Temperature range: -40°C ~ +125°C Dwell time: 10 minutes Transition time: 5 minutes Duration: 1000 cycles	JESD22-A104	No abnormal phenomenon was found. Functional test passed. No abnormal bond wire was found after DPA.
3	Unbiased Highly Accelerated Stress Test	elerated Stress Humidity: 85% RH		No abnormal phenome- non was found. Functional test passed.
4	Resistance to Solder Heat Test	Temperature: 25°C ± 5°C; Humidity: 55% RH ± 10% Solder: SAC305 Flux: SM-25 (Flux #2) Temperature: 260°C Duration: 10 seconds	JESD22-A106	No abnormal phenomenon was found.
5	Solderability Test	Temperature: 25°C ± 5°C; Humidity: 55% RH ± 10% Solder: SAC305 Flux: SM-25 (Flux #2) Temperature: 245°C Duration: 5 seconds	J-STD-002D	All samples of solderability test passed the test.
6	Physical Dimensions Test Measurement: Width, depth, and height of device		JESD22-B100	All samples of physical dimension test in the criteria.
7	Power Temperature Cycling Test	Temperature: 25°C ± 5°C; Humidity: 55% RH ± 10% Temperature range: -40°C to +125°C Dwell time: 10 minutes Ramp time: 30 minutes Voltage: PS1: 5V, PS2: 1440V, On: 5 minutes, Off: 5 minutes	JESD22-A105	No abnormal phenome- non was found. Functional test passed.
8	Terminal Strength Test	Temperature: 25°C ± 5°C; Humidity: 55% RH ± 10% Test lead: Two leads on each device Loading force: 8 oz Bend angle: 90 arcs Bend cycle: Three cycles	JESD22-B105D	No broken lead of the device after three cycles of bending test.



RELIABILITY TESTS **A STANDARD**

Standard: AEC-Q101, JESD22-A, J-STD-002

No.	Test	Test Specification	Test Standard	Test Limits
9	High Temperature Reverse Bias	Temperature: 25°C ± 5°C; Humidity: 55% RH ± 10% Temperature: 125°C Voltage: PS2: 1440V Duration: 1000 hours	MIL-STD-750 Method 1038	No abnormal phenome- non was found. Functional test passed.
10	High Humidity High Temperature Reverse Bias	Temperature: 25°C ± 5°C; Humidity: 55% RH ± 10% Temperature: 85°C; Humidity: 85% RH Voltage: PS2: 100V Duration: 1000 hours	JESD22-A101	No abnormal phenomenon was found. Functional test passed. No abnormal bond wire was found after DPA.
11	Temperature: $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$; Humidity: $55\% \text{ RH} \pm 10\%$ Human-Body Model Test Interval: > 1s; Zap 3 pulses Testing combinations: all to other pins		AEC-Q101-001 Rev.A	All samples of HBM test passed the test.
12	Temperature: $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$; Humidity: 55% RH $\pm 15\%$ Charge Device Model Test Interval: $> 1s$; Zap 3 pulses; Test humidity: $< 30\%$ RH Test pin: All pins		AEC-Q101-005 Rev.A	All samples of CDM test passed the test.



REVISION TABLE

Revision	Date	Status	Notes
001	01/10/2021	Initial release	Initial publication

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